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(54) **Title:** METHODS AND SYSTEMS FOR ATTACHING DIE IN STACKED-DIE PACKAGES

(57) **Abstract:** A method for producing a multiple-die device by attaching a die to a substrate using a first die-attach material having a first processing temperature and attaching a subsequent die using a second die-attach material having a second processing temperature such that the process of attaching the second die does not degrade the first die-attach material. For one embodiment, multiple dies are attached using each die-attach material. For one embodiment, the first die-attach material is a thermoplastic film and the second and subsequent die-attach materials are reformulations of the thermoplastic film.

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